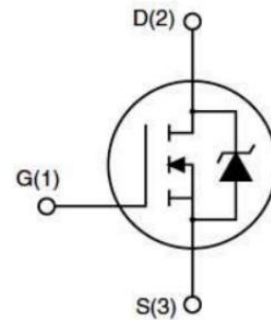


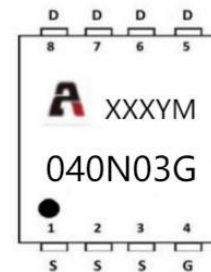
## Features

- 30V,80A  
 $R_{DS(on)} < 4.2m\Omega @ V_{GS}=10V$  TYP:3.6m $\Omega$   
 $R_{DS(on)} < 7.0m\Omega @ V_{GS}=10V$  TYP:5.5m $\Omega$
- Advanced Trench Technology
- High Power and current handing capability
- Lead free product is acquired



## Applications

- Load Switch
- Synchronous Rectification



**Marking and pin Assignment**

## Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity (PCS)
040N03G	AP040N03G	PDFN5X6	-	-	5000

## ABSOLUTE MAXIMUM RATINGS ( $T_J=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	30	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current ( $T_c=25^\circ\text{C}$ ) <sup>(1)</sup>	$I_D$	80	A
Continuous Drain Current ( $T_c=100^\circ\text{C}$ )	$I_D$	48	A
Pulsed Drain Current <sup>(2,3)</sup>	$I_{DM}$	320	A
Drain Power Dissipation <sup>(1)</sup>	$P_D$	30	W
Single Pulsed Avalanche Energy	$E_{AS}$	200	mJ
Thermal Resistance from Junction to Case <sup>(1)</sup>	$R_{\theta JC}$	4.17	$^\circ\text{C}/\text{W}$
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	62.5	$^\circ\text{C}/\text{W}$
Junction Temperature	$T_J$	-55~ +150	$^\circ\text{C}$
Storage Temperature	$T_{STG}$	-55~ +150	$^\circ\text{C}$

**MOSFET ELECTRICAL CHARACTERISTICS**( $T_J=25^\circ\text{C}$  unless otherwise noted)

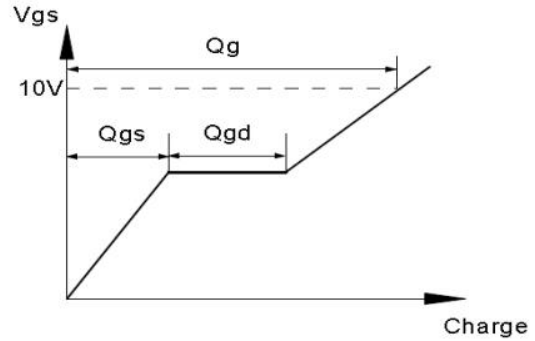
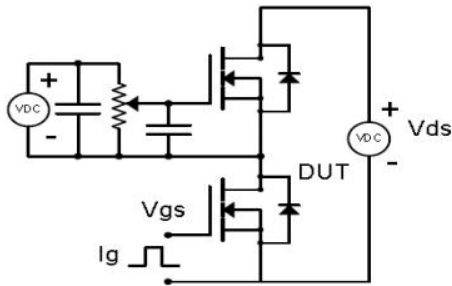
Parameter	Symbol	Test Condition	Min	Type	Max	Unit
<b>Static Characteristics</b>						
Drain-source breakdown voltage	$V_{(BR)DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	30	-	-	V
Zero gate voltage drain current	$I_{DSS}$	$V_{DS} = 30V, V_{GS} = 0V$	-	-	1	$\mu A$
Gate-body leakage current	$I_{GSS}$	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	$\pm 100$	nA
Gate threshold voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\mu A$	1	1.5	2	V
Drain-source on-resistance <sup>(4)</sup>	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 30A$	-	3.6	4.2	m $\Omega$
		$V_{GS} = 4.5V, I_D = 20A$	-	5.5	7.0	
<b>Dynamic characteristics<sup>(5)</sup></b>						
Input Capacitance	$C_{iss}$	$V_{DS} = 25V, V_{GS} = 0V, f = 1MHz$	-	1950	2350	pF
Output Capacitance	$C_{oss}$		-	320	-	
Reverse Transfer Capacitance	$C_{rss}$		-	240	-	
<b>Switching characteristics<sup>(5)</sup></b>						
Turn-on delay time	$t_{d(on)}$	$V_{DD} = 15V, I_D = 15A, R_G = 3.3\Omega,$ $V_{GS} = 10V$	-	13	-	nS
Turn-on rise time	$t_r$		-	36	-	
Turn-off delay time	$t_{d(off)}$		-	43	-	
Turn-off fall time	$t_f$		-	16	-	
Total Gate Charge	$Q_g$	$V_{DS} = 24V, I_D = 20A,$ $V_{GS} = 10V$	-	42	84	nC
Gate-Source Charge	$Q_{gs}$		-	3.9	-	
Gate-Drain Charge	$Q_{gd}$		-	14	-	
<b>Source-Drain Diode characteristics</b>						
Diode Forward voltage <sup>(4)</sup>	$V_{SD}$	$T_J = 25^\circ\text{C}, V_{GS} = 0V, I_S = 30A$	-	-	1.2	V
Diode Forward current	$I_S$	$T_C = 25^\circ\text{C}$	-	-	80	A
Body Diode Reverse Recovery Time	$t_{rr}$	$T_J = 25^\circ\text{C}, I_F = 10A, di/dt = 100A/\mu s$	-	16	-	nS
Body Diode Reverse Recovery Charge	$Q_{rr}$		-	5	-	nC

**Notes:**

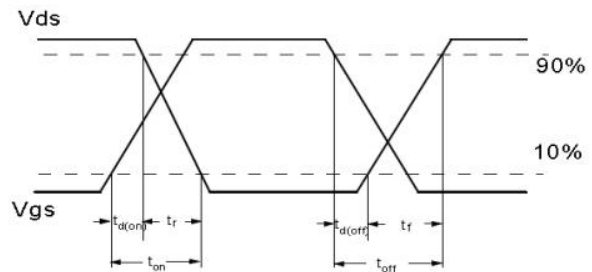
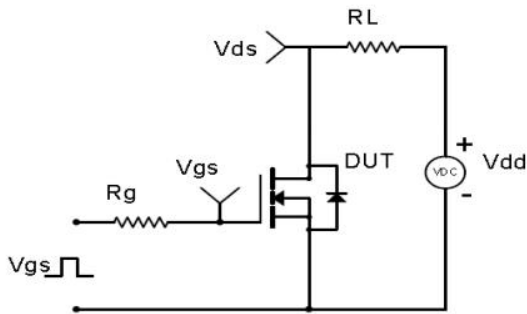
- 1) Surface Mounted on 1 in<sup>2</sup> pad area,  $t \leq 10$  sec
- 2) Pulse width  $\leq 10\mu s$ , duty cycle  $\leq 1\%$
- 3) Limited by bonding wire
- 4) Pulse width  $\leq 300\mu s$ , duty cycle  $\leq 2\%$
- 5) Guaranteed by design, not subject to production testing

**Test Circuit & Waveform**

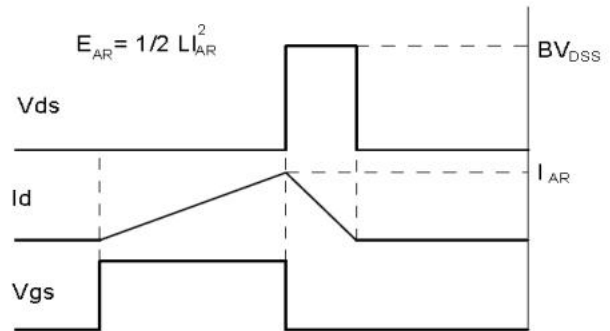
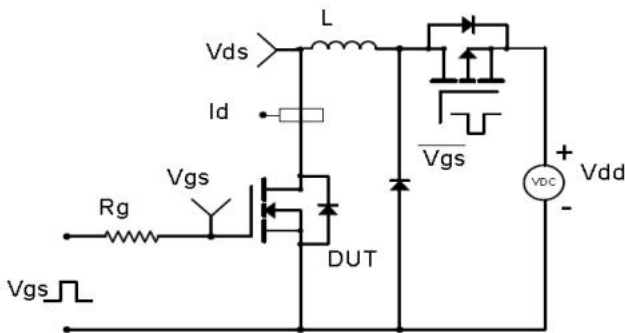
Gate Charge Test Circuit & Waveform



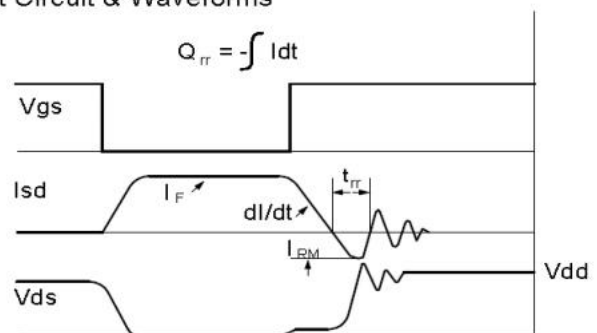
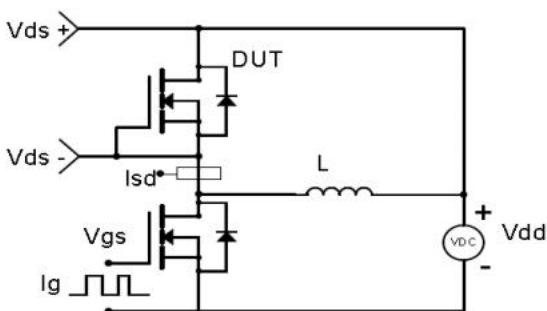
Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching (UIS) Test Circuit & Waveforms

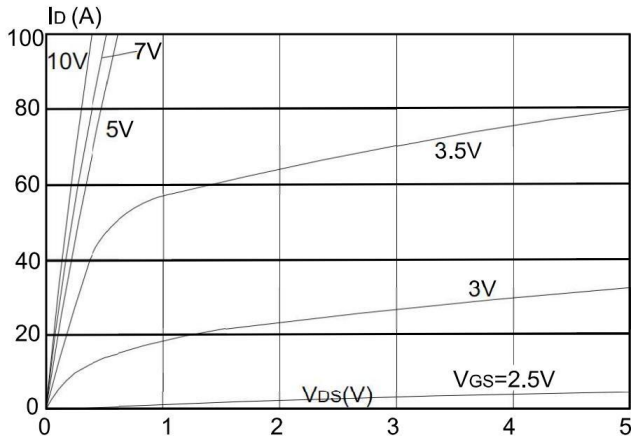


Diode Recovery Test Circuit & Waveforms

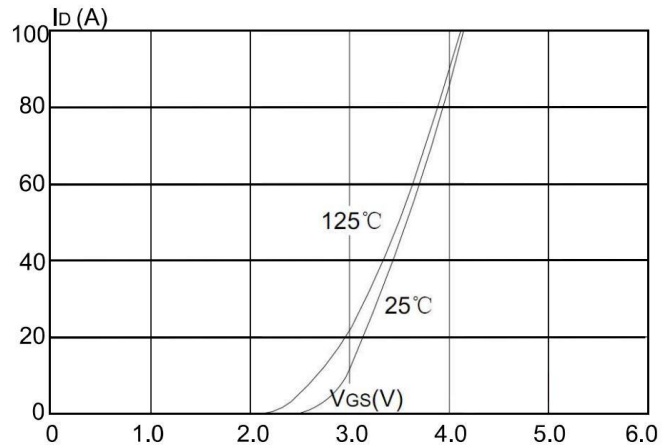


## Typical Characteristics

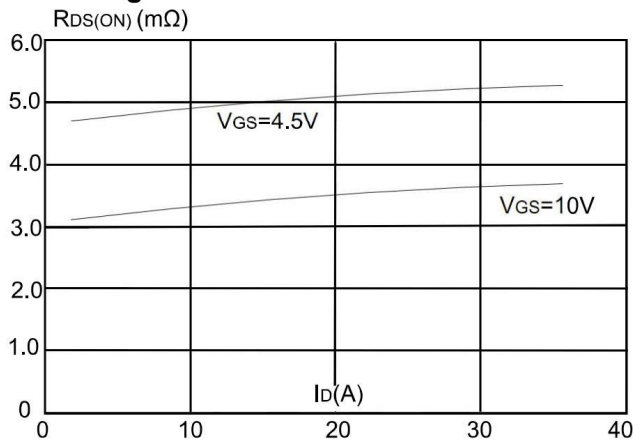
**Figure 1: Output Characteristics**



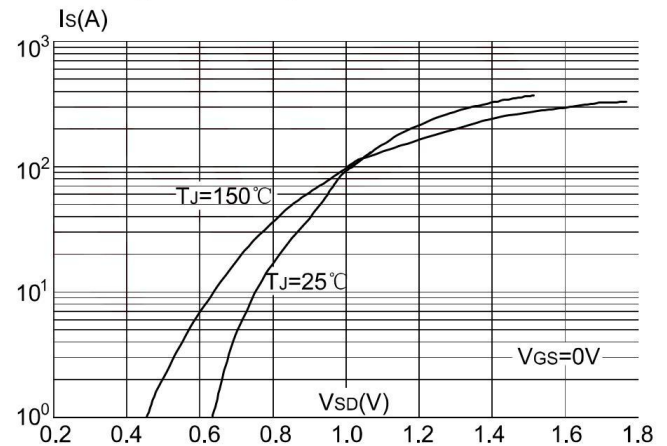
**Figure 2: Typical Transfer Characteristics**



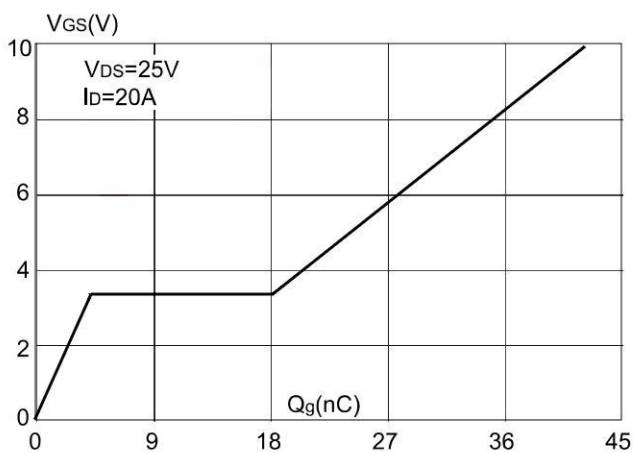
**Figure 3: On-resistance vs. Drain Current**



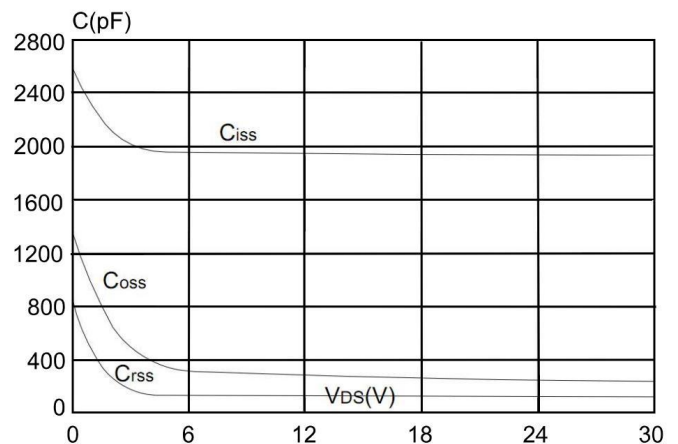
**Figure 4: Body Diode Characteristics**



**Figure 5: Gate Charge Characteristics**

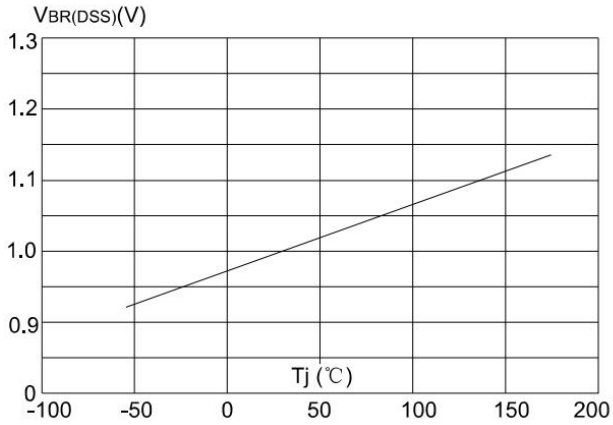


**Figure 6: Capacitance Characteristics**

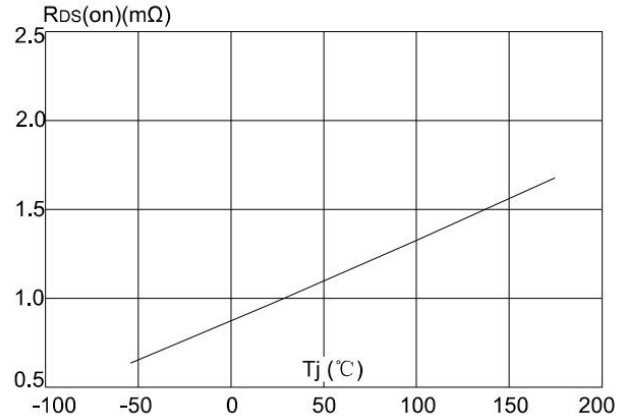


## Typical Characteristics

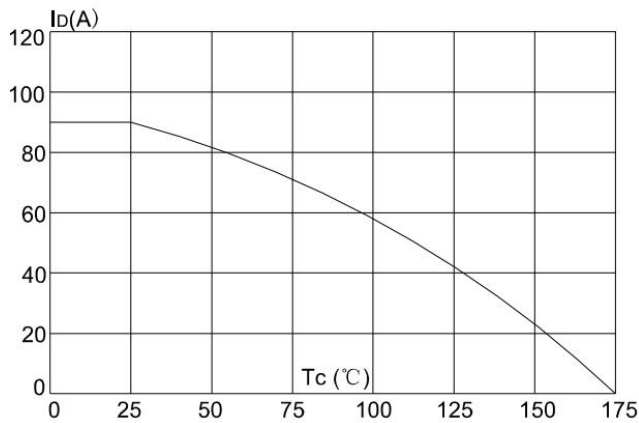
**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature



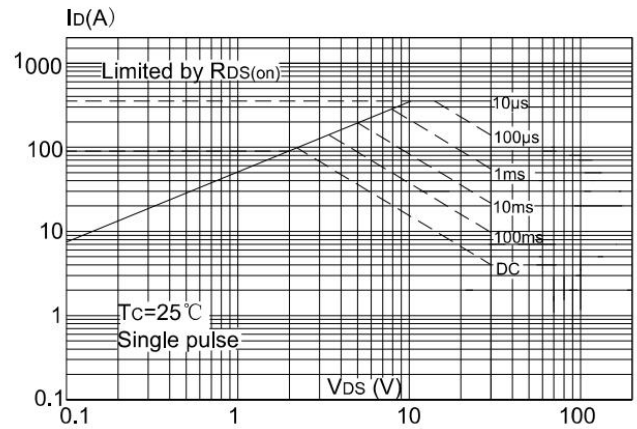
**Figure 8:** Normalized on Resistance vs. Junction Temperature



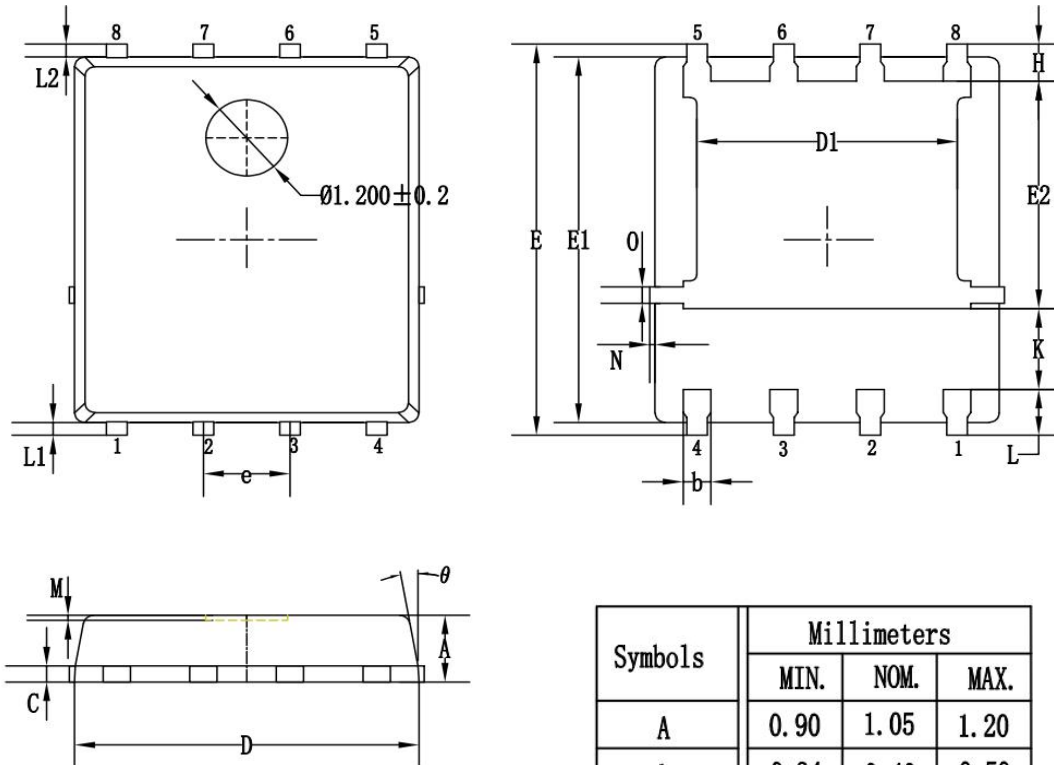
**Figure 9:** Maximum Continuous Drain Current vs. Case Temperature



**Figure 10:** Maximum Safe Operating Area



**PDFN5X6 Package Information**



Symbols	Millimeters		
	MIN.	NOM.	MAX.
A	0.90	1.05	1.20
b	0.34	0.40	0.50
C	0.20	0.25	0.35
D	4.80	5.05	5.20
D1	3.72	3.82	3.92
E	5.95	6.15	6.30
E1	5.60	5.75	5.90
E2	3.47	3.57	3.67
e	1.27 BSC.		
H	0.48	0.58	0.68
K	1.17	1.27	1.37
L	0.64	0.74	0.84
L1/L2	0.20 REF.		
$\theta$	8°	10°	12°
M	0.08 REF.		
N	0	-	0.15
O	0.25 REF.		

## Revision History

Revision	Release	Remark
V1.0	2024/03/16	Initial Release

## Disclaimer

The information given in this document describes the independent performance of the product, but similar performance is not guaranteed under other working conditions, and cannot be guaranteed when installed with other products or equipment. To achieve the required performance of the product in actual scenarios, the customer should conduct a complete application test to assess the functionality of the product.

Allpower assumes no responsibility for equipment failures result from using products at values that exceed the ratings, operating conditions, or other parameters listed in the product specifications.

The product described in this specification is not applicable for aerospace or other applications which requires high reliability. Customers using or selling these products for use in medical, life-saving, or life-sustaining applications do so at their own risk and agree to fully indemnify.

Due to product or technical improvements, the information described or contained herein may be changed without prior notice.